ANNEXURE A: OUR MATERIAL TRADEMARKS, BRAND NAMES AND OTHER INTELLECTUAL PROPERTY RIGHTS

A.1 TRADEMARKS

As at the LPD, we have 21 trademarks in Malaysia and Chinese Mainland, which are registered for our operations, details of which are stipulated in the table below:-

(i) Malaysia

No.	Trademark	Registered owner / Applicant	Registration / Application no.	Place of registration	Expiry date / Application date	Class / Description of trademark
1.	SUIWA	SQAI	TM2025041772(1)	Malaysia	Application date: 27 November 2025	Class 9 - Electronic circuits; Flexible printed circuits; Printed circuit boards incorporating integrated circuits; Semiconductor integrated circuits; Electronic components for integrated circuit cards; Printed circuit boards; Electronic connectors; Electronic chips (semiconductors) for the manufacture of integrated circuits; Electronic semiconductors; Semiconductors; Semiconductors (integrated circuits)
2.	SUIWA	SQAI	TM2025041775(1)	Malaysia	Application date: 27 November 2025	Class 17 - Polymer films and sheets for use in the manufacture of printed circuit boards; Polymer films for use in the manufacture of electronic circuits; Films and sheets made from polymers for use in the manufacture of printed circuit boards; Insulating film; Polymer films for use in manufacture; Electrical insulating materials; Insulating materials; Thermal insulating materials

ANNEXURE A: OUR MATERIAL TRADEMARKS, BRAND NAMES AND OTHER INTELLECTUAL PROPERTY RIGHTS (CONT'D)

No.	Trademark	Registered owner / Applicant	Registration / Application no.	Place of registration	Expiry date / Application date	Class / Description of trademark
3.	SUIWA	SQAI	TM2025041779(1)	Malaysia	Application date: 27 November 2025	Class 36 - Financial administration of property portfolios; Financial management of property portfolios; Financing of property development; Property investment services; Property management services; Property investment management; Property management; Providing online information relating to financial, banking, insurance and investment services; Real estate funds investment services; Real estate investment services; Property investment and management services; Property investment banking services; Providing on-line information relating to financial, banking, insurance and investment services; Investment services; Investment management services; Capital investment in real estate; Real estate brokerage services
4.	SUIWA	SQAI	TM2025041783(1)	Malaysia	Application date: 27 November 2025	Class 40 - Custom manufacturing; Custom assembling of materials for others; Custom manufacture of semiconductor circuits; Custom manufacture of semiconductor components; Custom manufacturing and assembling services relating to semiconductor parts and integrated circuits
5.	SUIWA	SQAI	TM2025041786(1)	Malaysia	Application date: 27 November 2025	Class 42 - Scientific and technological services and research and design relating thereto; Scientific and industrial analysis and research services; Design and development of computer hardware and software; Prototype design services

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No.	Trademark	Registered owner / Applicant	Registration / Application no.	Place of registration	Expiry date / Application date	Class / Description of trademark
6.	SQAI	SQAI	TM2026004925(1)	Malaysia	Application date: 11 February 2026	Class 9 - Electronic circuits; Flexible printed circuits; Printed circuit boards incorporating integrated circuits; Semiconductor integrated circuits; Electronic components for integrated circuit cards; Printed circuit boards; Electronic connectors; Electronic chips (semiconductors) for the manufacture of integrated circuits; Electronic semiconductors; Semiconductors; Semiconductors (integrated circuits)
7.	SQAI	SQAI	TM2026004931(1)	Malaysia	Application date: 11 February 2026	Class 17 - Polymer films and sheets for use in the manufacture of printed circuit boards; Polymer films for use in the manufacture of electronic circuits; Films and sheets made from polymers for use in the manufacture of printed circuit boards; Insulating film; Polymer films for use in manufacture; Electrical insulating materials; Insulating materials; Thermal insulating materials
8.	SQAI	SQAI	TM2026004933(1)	Malaysia	Application date: 11 February 2026	Class 40 - Custom manufacturing; Custom assembling of materials for others; Custom manufacture of semiconductor circuits; Custom manufacture of semiconductor components; Custom manufacturing and assembling services relating to semiconductor parts and integrated circuits
9.	SQAI	SQAI	TM2026004935(1)	Malaysia	Application date: 11 February 2026	Class 42 - Scientific and technological services and research and design relating thereto; Scientific and industrial analysis and research services; Design and development of computer hardware and software; Prototype design services

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No.	Trademark	Registered owner / Applicant	Registration / Application no.	Place of registration	Expiry date / Application date	Class / Description of trademark
10.	QDOS	QFSB	05021403	Malaysia	Expiry date: 19 December 2035	Class 9 - Flexible printed circuits board and components thereof; all included in class 9
11.	QDOS	QFSB	05021404	Malaysia	Expiry date:19 December 2035	Class 38 - Telecommunications; all included in class 38
12.	QDOS	QFSB	05021405	Malaysia	Expiry date:19 December 2035	Class 42 - Scientific and technological services and research and design relating thereto; industrial analysis and research services; design and development of computer hardware and software; legal services; all included in class 42
13.	QDOS	QFSB	TM2025041770⁽¹⁾	Malaysia	Application date: 27 November 2025	Class 17 - Polymer films and sheets for use in the manufacture of printed circuit boards; Polymer films for use in the manufacture of electronic circuits; Films and sheets made from polymers for use in the manufacture of printed circuit boards; Insulating film; Polymer films for use in manufacture; Electrical insulating materials; Insulating materials; Thermal insulating materials
14.	QDOS	QFSB	TM2025041771⁽¹⁾	Malaysia	Application date: 27 November 2025	Class 40 - Custom manufacturing; Custom assembling of materials for others; Custom manufacture of semiconductor circuits; Custom manufacture of semiconductor components; Custom manufacturing and assembling services relating to semiconductor parts and integrated circuits

Note:-

(1) *As at the LPD, the trademark application is under substantive examination and/or formality validation in Malaysia.*

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(ii) Chinese Mainland

No.	Trademark	Registered owner	Registration no.	Place of registration	Expiry date	Class/ Description of trademark
1.		SHTEI	48503113	Chinese Mainland	27 March 2031	Class 36 - Commercial residential property sales, apartment management, real estate management, real estate brokerage, leasing or renting of buildings, real estate appraisal, real estate rental, office (real estate) rental, shared office rental; real estate agency
2.		SHTEI	48494561	Chinese Mainland	6 April 2031	Class 35 - Leasing of advertising space and advertising materials, commercial management support, organizing commercial or advertising exhibitions, provision of commercial information, management support for tender response, commercial intermediary services, commercial project management services for construction projects, sales promotion on behalf of others, providing an online marketplace for buyers and sellers of goods and services, sponsorship solicitation
3.		SHTEI	48506133	Chinese Mainland	13 April 2031	Class 36 - Apartment management, real estate management, real estate brokerage, real estate agency, residential property sales, real estate rental, office (real estate) leasing, co-working office rental, building leasing and rental, real estate appraisal

ANNEXURE A: OUR MATERIAL TRADEMARKS, BRAND NAMES AND OTHER INTELLECTUAL PROPERTY RIGHTS (CONT'D)

No.	Trademark	Registered owner	Registration no.	Place of registration	Expiry date	Class/ Description of trademark
4.		SHTEI	48485622	Chinese Mainland	27 March 2031	Class 35 - Leasing of advertising space and advertising materials, commercial intermediary services, management support for tender response, provision of commercial information, organizing commercial or advertising exhibitions, commercial project management services for construction projects, commercial management support, sales promotion on behalf of others, providing an online marketplace for buyers and sellers of goods and services, sponsorship solicitation
5.	SUIWA	SHTEI	35082441	Chinese Mainland	20 July 2029	Class 9 - Data carriers storing printed fonts, printed circuits, integrated circuits, integrated circuit modules, electronic integrated circuits, circuit boards with integrated circuits, large-scale integrated circuits, chips (integrated circuits), flexible printed circuits board and components thereof
6.	瑞华高科	SHTEI	34531080	Chinese Mainland	6 August 2029	Class 9 - Data carriers with stored printing fonts, printed circuits, integrated circuits, integrated circuit modules, electronic integrated circuits, circuit boards with integrated circuits, large-scale integrated circuits, chips (integrated circuits), flexible printed circuit boards, printed circuit boards
7.		SHTEI	5083054	Chinese Mainland	20 December 2028	Class 9 - Integrated circuit, integrated circuit blocks, flexible printed circuit boards, printed circuits, phototubes, flexible printed circuits, optical fibers (optical fibres), semiconductor devices, thermocompression conductive connecting wires, fluorescent screens

A.2 PATENTS

As at the LPD, we have 54 patents in Malaysia, Chinese Mainland and USA, which are registered for our operations, details of which are stipulated in the table below:-

(i) Malaysia

No.	Patent	Registered owner	Registration no.	Place of registration	Date of grant
1.	Pallet Assembly For Flexible Circuit Board	QFSB	MY-158144-A	Malaysia	15 September 2016
2.	A Method Of Depositing An Object Onto Wiring Board And A System Using The Same	QFSB	MY-166697-A	Malaysia	18 July 2018
3.	An Integrated Circuit Substrate And Method Of Producing Thereof	QFSB	MY-177199-A	Malaysia	9 September 2020
4.	Integrated Circuit Package Having Pin Up Interconnect	QFSB	MY-172923-A	Malaysia	13 December 2019
5.	Single Layer Integrated Circuit Package	QFSB	MY-181637-A	Malaysia	30 December 2020
6.	An Integrated Circuit Substrate Having a Recess For Receiving A Solder Fillet	QFSB	MY-204583-A	Malaysia	5 September 2024
7.	Integrated Circuit Package Having Pin Up Interconnect	QFSB	MY-199582-A	Malaysia	7 November 2023
8.	Integrated Circuit Package	QISB	MY-193261-A	Malaysia	28 September 2022

(ii) Chinese Mainland

No.	Patent	Registered owner	Registration no.	Place of registration	Date of grant
1.	An SMT Carrier for Flexible Circuit Boards	SHTEI	202420090569.0	Chinese Mainland	7 March 2025
2.	A Flying Probe Fixture for Testing Extra-Long Flexible Circuit Boards	SHTEI	202320370333.8	Chinese Mainland	29 August 2023
3.	A Multilayer Flexible Circuit Board	SHTEI	202320364509.9	Chinese Mainland	29 August 2023
4.	An Impedance Test Fixture for Flexible Circuit Boards	SHTEI	202320218977.5	Chinese Mainland	29 August 2023
5.	A Double-Sided Flexible Circuit Board	SHTEI	202222439965.3	Chinese Mainland	31 January 2023
6.	A Manufacturing Method for Extra-Long Flexible Circuit Boards	SHTEI	202210365811.6	Chinese Mainland	25 October 2024
7.	A Double-Sided FPC and Its Manufacturing Method	SHTEI	202210059640.4	Chinese Mainland	29 March 2024
8.	A Multilayer Printed Circuit Board with Misalignment Detection Structure	SHTEI	202220121333.X	Chinese Mainland	12 July 2022
9.	A Plasma Protection Fixture for FPC	SHTEI	202220106596.3	Chinese Mainland	12 July 2022
10.	An FPC Test Sampling Device	SHTEI	202123431860.5	Chinese Mainland	12 July 2022
11.	An FPC Bending Test Fixture	SHTEI	202123220360.7	Chinese Mainland	12 July 2022
12.	A Waste Disposal Fixture for Asymmetric Rigid-Flex Boards	SHTEI	202122870469.9	Chinese Mainland	24 June 2022
13.	A Plating Fixture for FPC Boards	SHTEI	202121263986.3	Chinese Mainland	11 February 2022
14.	An Electrical Performance Test Device for Multilayer FPCs	SHTEI	202121264986.5	Chinese Mainland	11 February 2022
15.	A Reinforcement Lamination Fixture for Flexible Circuit Boards with Electronic Components	SHTEI	202120956456.0	Chinese Mainland	11 February 2022
16.	A Vacuum Platform for Removing Carrier Films	SHTEI	202120965045.8	Chinese Mainland	8 April 2022
17.	A Vision Inspection Machine for FPC Product Tray Packaging	SHTEI	202021506480.6	Chinese Mainland	2 March 2021

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No.	Patent	Registered owner	Registration no.	Place of registration	Date of grant
18.	A Vision Inspection Machine for FPC Gold Finger Cutting Offset	SHTEI	202021295369.7	Chinese Mainland	2 March 2021
19.	A Vision Inspection Device for LEDs on FPCAs	SHTEI	202020636965.0	Chinese Mainland	4 December 2020
20.	A High-Precision FPC Reinforcement Lamination Fixture	SHTEI	202020642991.4	Chinese Mainland	4 December 2020
21.	A Manufacturing Method for Ultra-Thin Pseudo-Void Double-Layer FPC Products	SHTEI	202010207049.X	Chinese Mainland	20 April 2021
22.	A Fixture for Reinforcement Lamination of Single FPC Products	SHTEI	202020378548.0	Chinese Mainland	29 September 2020
23.	An SMT Component Alignment and Lamination Fixture	SHTEI	202020257903.9	Chinese Mainland	4 December 2020
24.	A Partially Ultra-Thin Hollowed Double-Layer FPC Product and Its Manufacturing Method	SHTEI	202010138370.7	Chinese Mainland	2 March 2021
25.	A Panel Processing Method for Flexible Circuit Boards	SHTEI	201811632604.2	Chinese Mainland	24 March 2020
26.	A Manufacturing Method for Ultra-Thin Single-Sided FPC Products	SHTEI	201811313317.5	Chinese Mainland	3 December 2019
27.	A Flexible Heating Circuit Board	SHTEI	201821818390.3	Chinese Mainland	27 September 2019
28.	A Fixture Capable of Four-Wire Testing	SHTEI	201821818388.6	Chinese Mainland	12 July 2019
29.	A Foam Bending Mold	SHTEI	201821821319.0	Chinese Mainland	12 July 2019
30.	A Gold Plating Basket for Flexible Circuit Boards	SHTEI	201820280465.0	Chinese Mainland	19 October 2018
31.	A Bending Test Device for Flexible Circuit Boards	SHTEI	201820144506.3	Chinese Mainland	10 August 2018
32.	A Fixture for Laminating 3D Auxiliary Materials onto Flexible Circuit Boards	SHTEI	201820126653.8	Chinese Mainland	10 August 2018
33.	A Gold Finger Punching Die for Flexible Circuit Boards	SHTEI	201820126707.0	Chinese Mainland	7 September 2018
34.	A Microphone Test Device for Flexible Circuit Boards	SHTEI	201820101506.5	Chinese Mainland	7 September 2018

No.	Patent	Registered owner	Registration no.	Place of registration	Date of grant
35.	A Tooling Fixture for Reinforcement Lamination of Flexible Circuit Boards	SHTEI	201721192651.0	Chinese Mainland	23 March 2018
36.	A Fixture for Testing the Flex Durability of Flexible Circuit Boards	SHTEI	201721192851.6	Chinese Mainland	23 March 2018
37.	A Dispensing Fixture	SHTEI	201620336348.2	Chinese Mainland	7 September 2016
38.	A Processing Method for Multilayer Flexible Circuit Boards	SHTEI	201510559712.1	Chinese Mainland	19 February 2019
39.	A Manufacturing Method for Circuit Boards	SHTEI	201310209127.X	Chinese Mainland	17 February 2016
40.	A packaging box for a flexible printed circuit board	SHTEI	202423119234.6	Chinese Mainland	25 November 2025
41.	FPC board code-scanning test fixture	SHTEI	202422870588.8	Chinese Mainland	31 October 2025
42.	Hot Melt Machine for Circuit Boards	SHTEI	2025200680600	Chinese Mainland	6 January 2026

(iii) USA

No.	Patent	Registered owner	Registration no.	Place of registration	Date of grant
1.	Method And System For Depositing An Object Onto A Wiring Board	QFSB	US 9,609,759 B2	USA	28 March 2017
2.	Integrated Circuit Substrate And Method Of Producing Thereof	QFSB	US 10,461,004 B2	USA	29 October 2019
3.	Integrated Circuit Package Having Pin Up Interconnect	QFSB	US 10,049,935 B2	USA	14 August 2018
4.	Single Layer Integrated Circuit Package	QFSB	US 10,553,475 B2	USA	4 February 2020